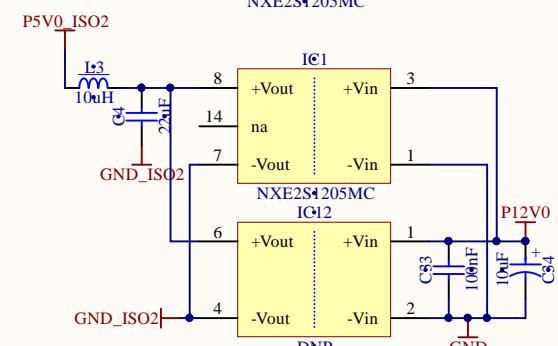
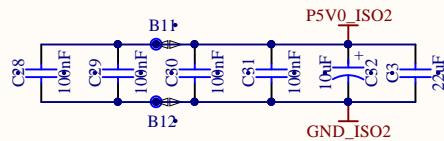
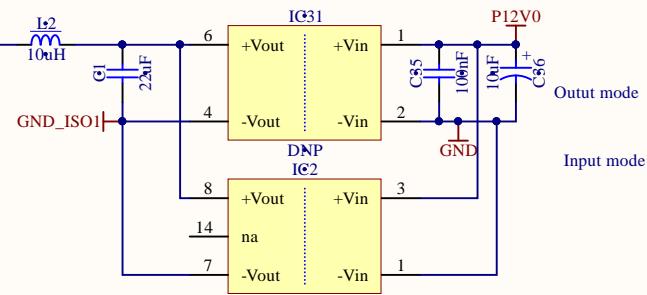
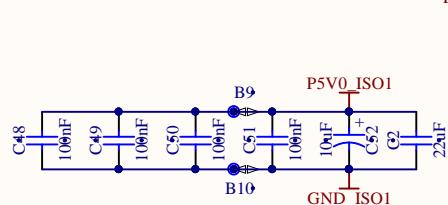
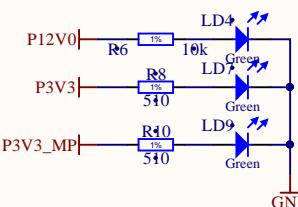
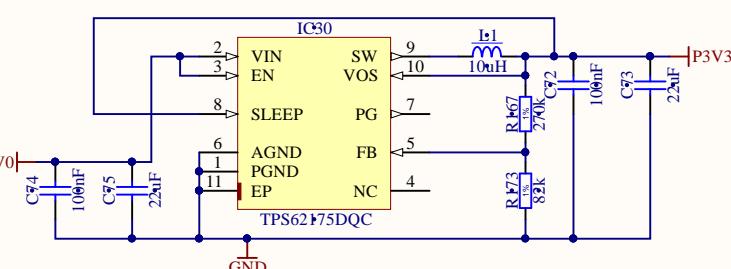
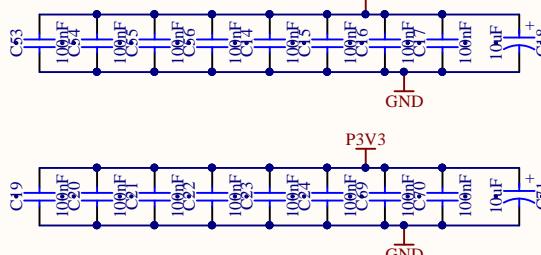


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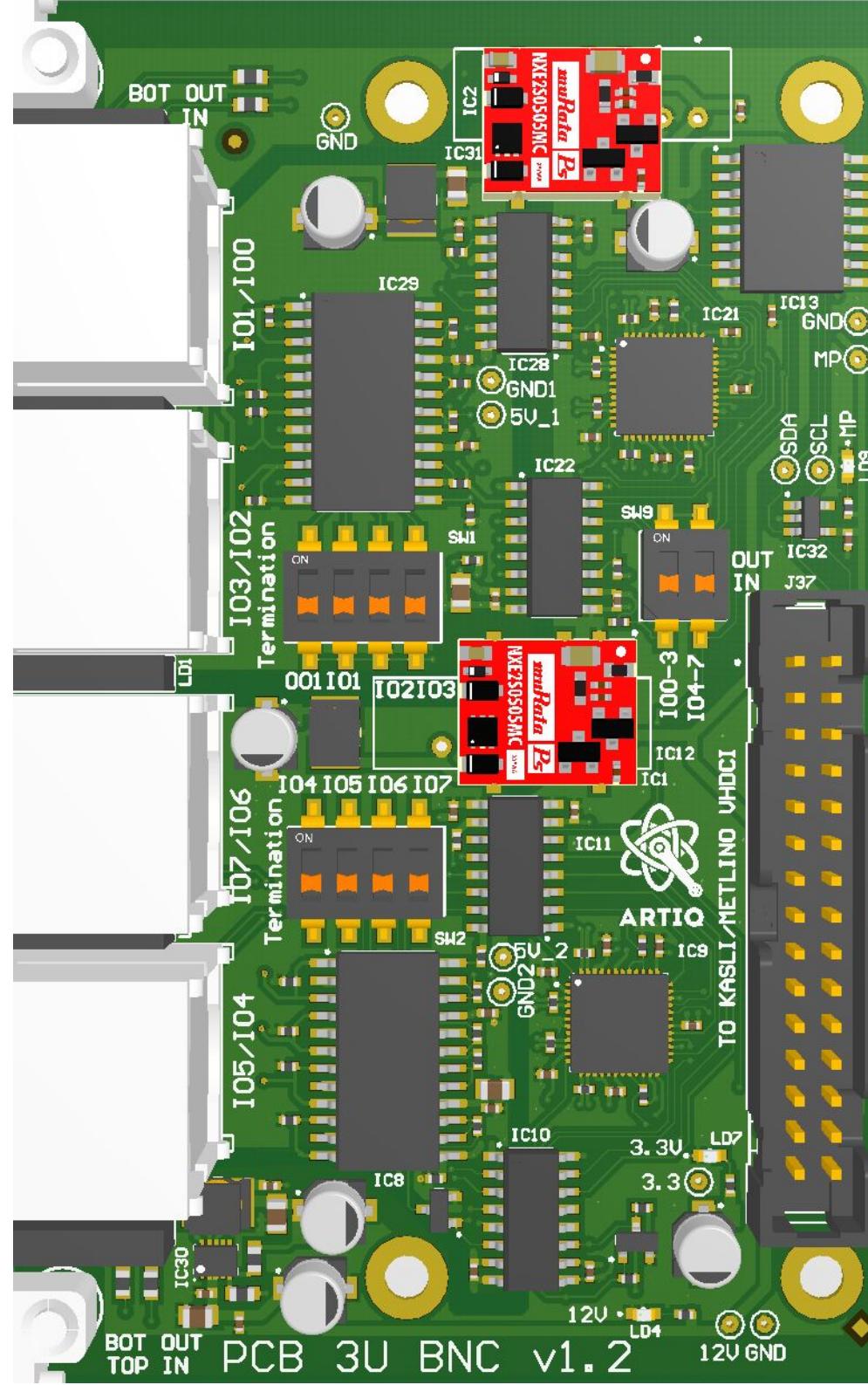


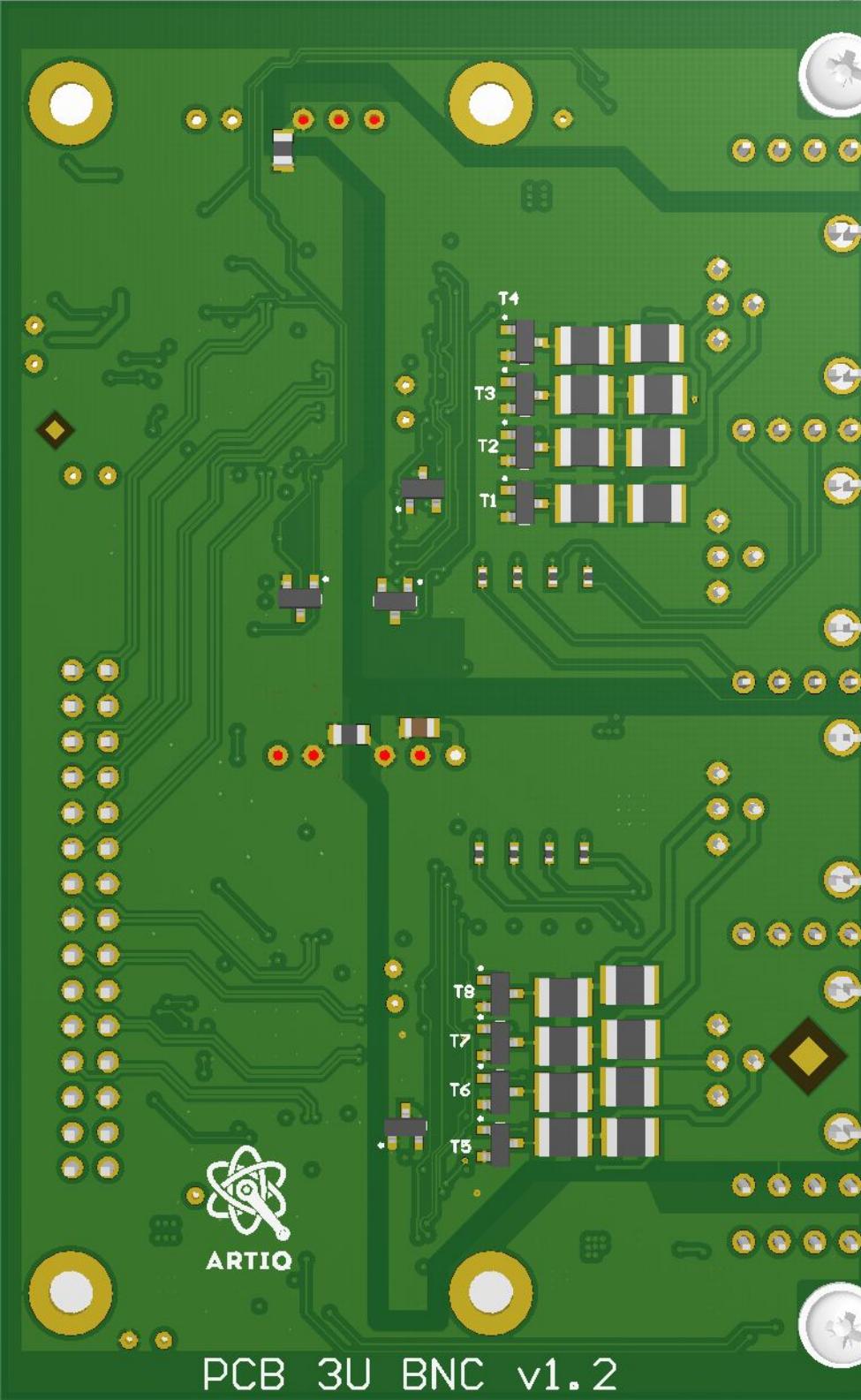
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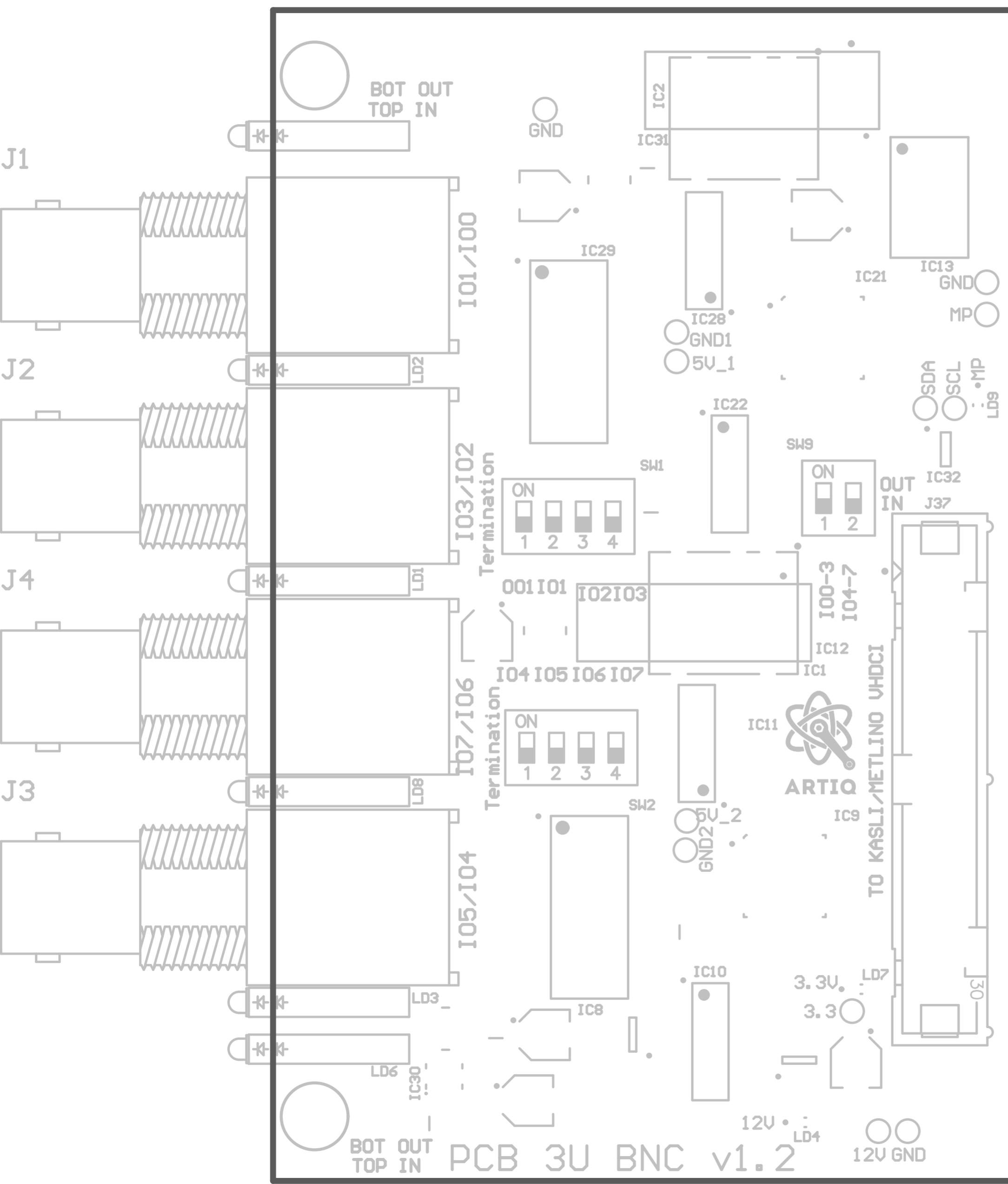


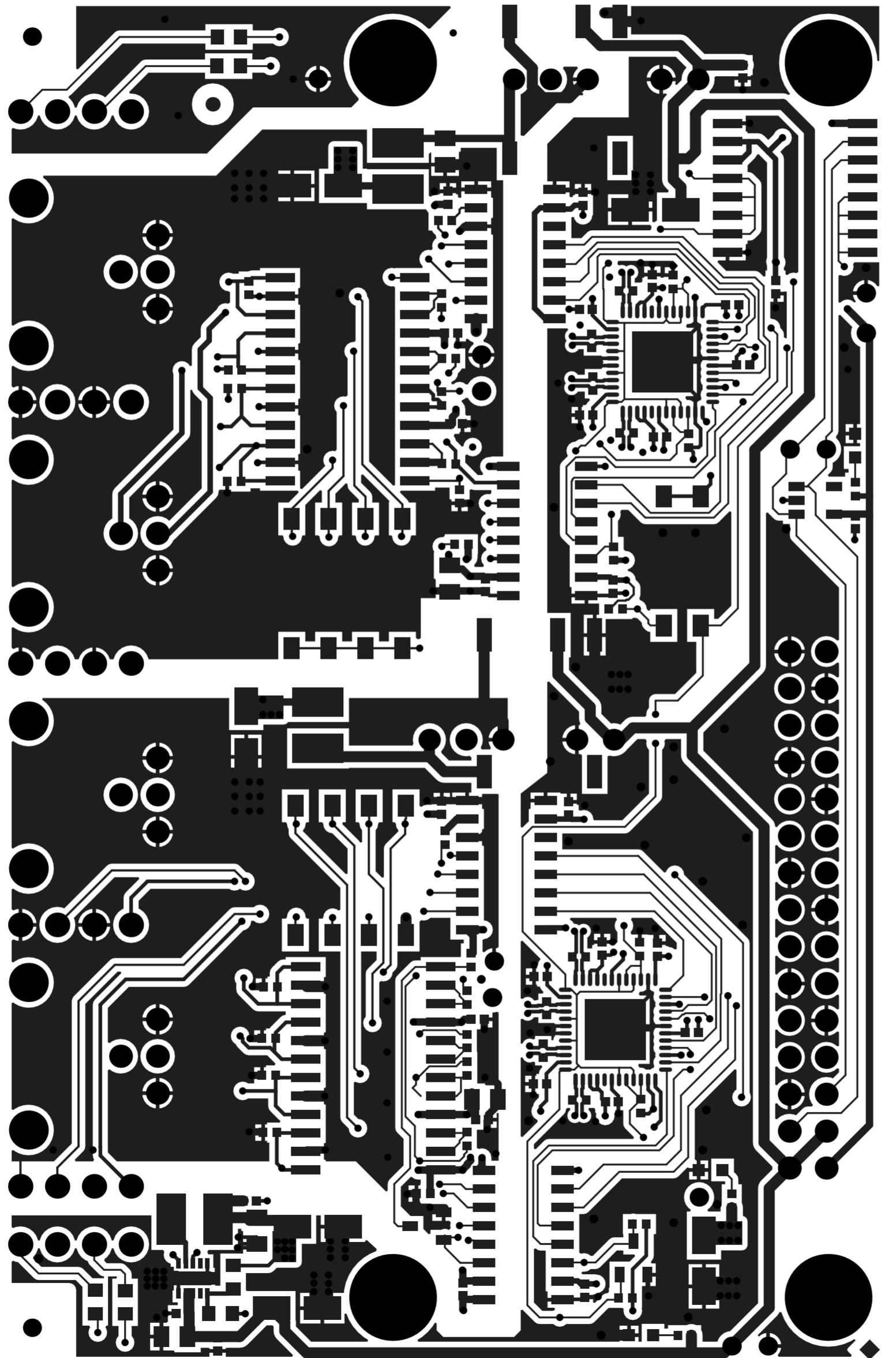
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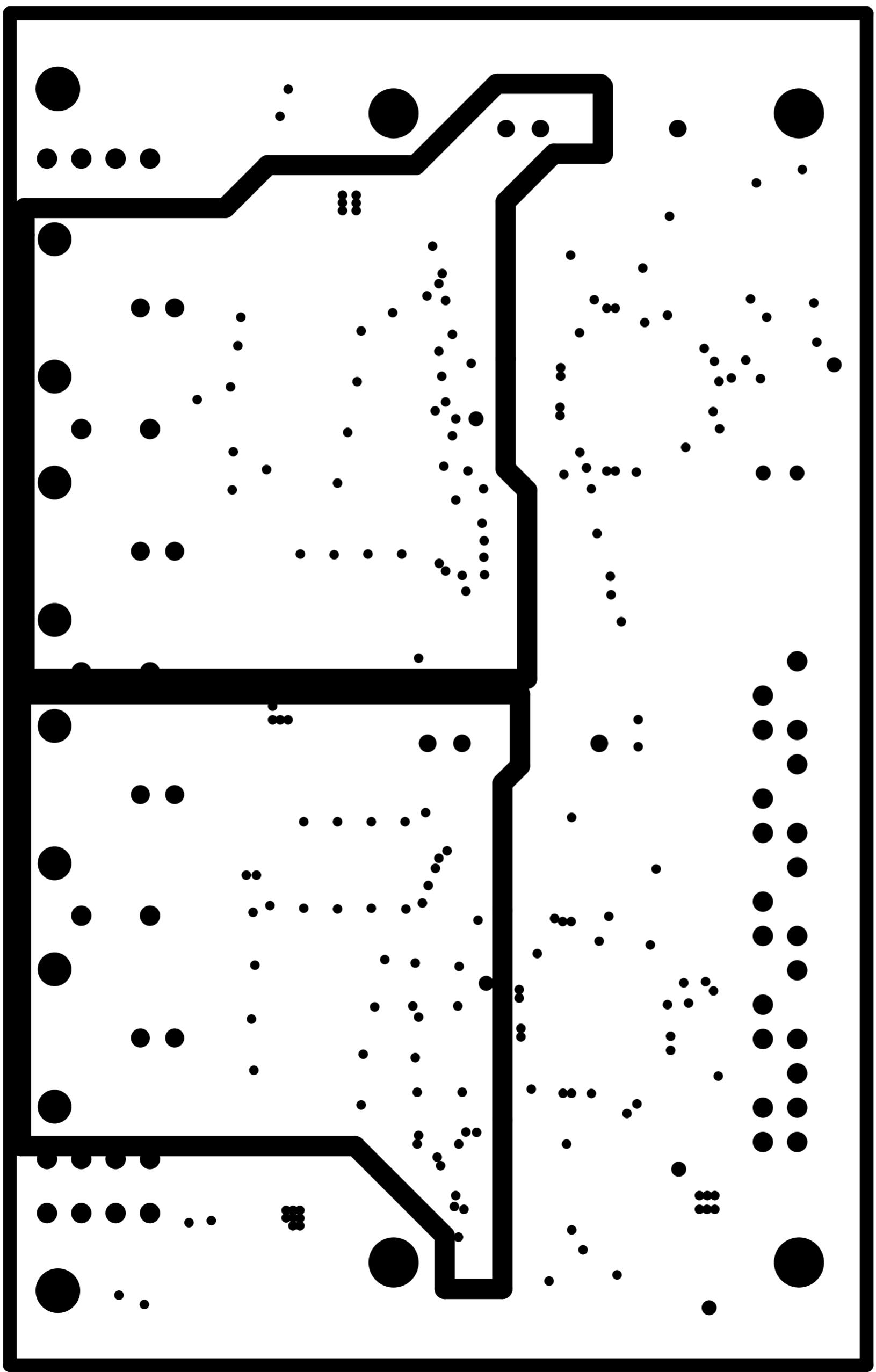


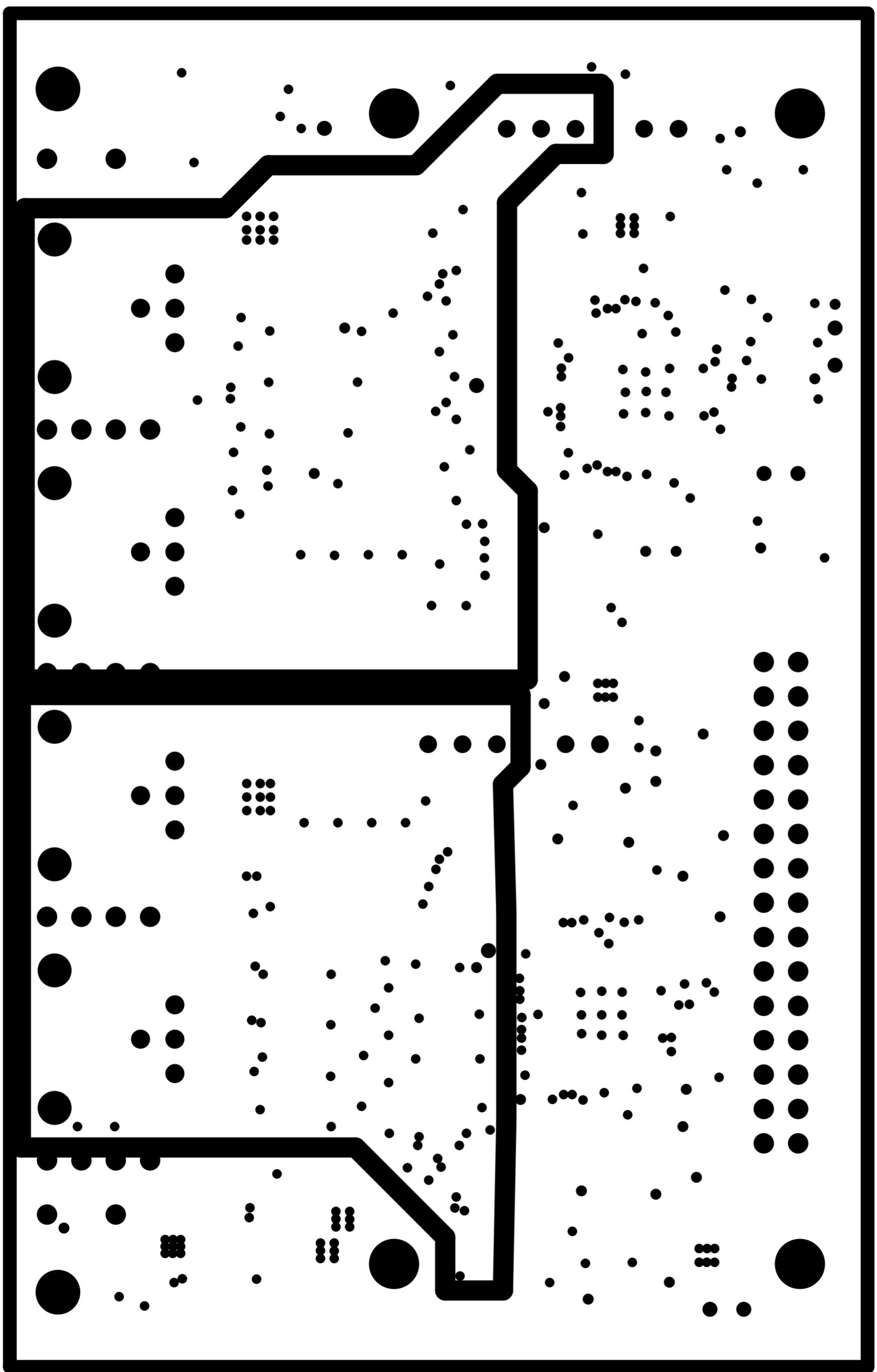


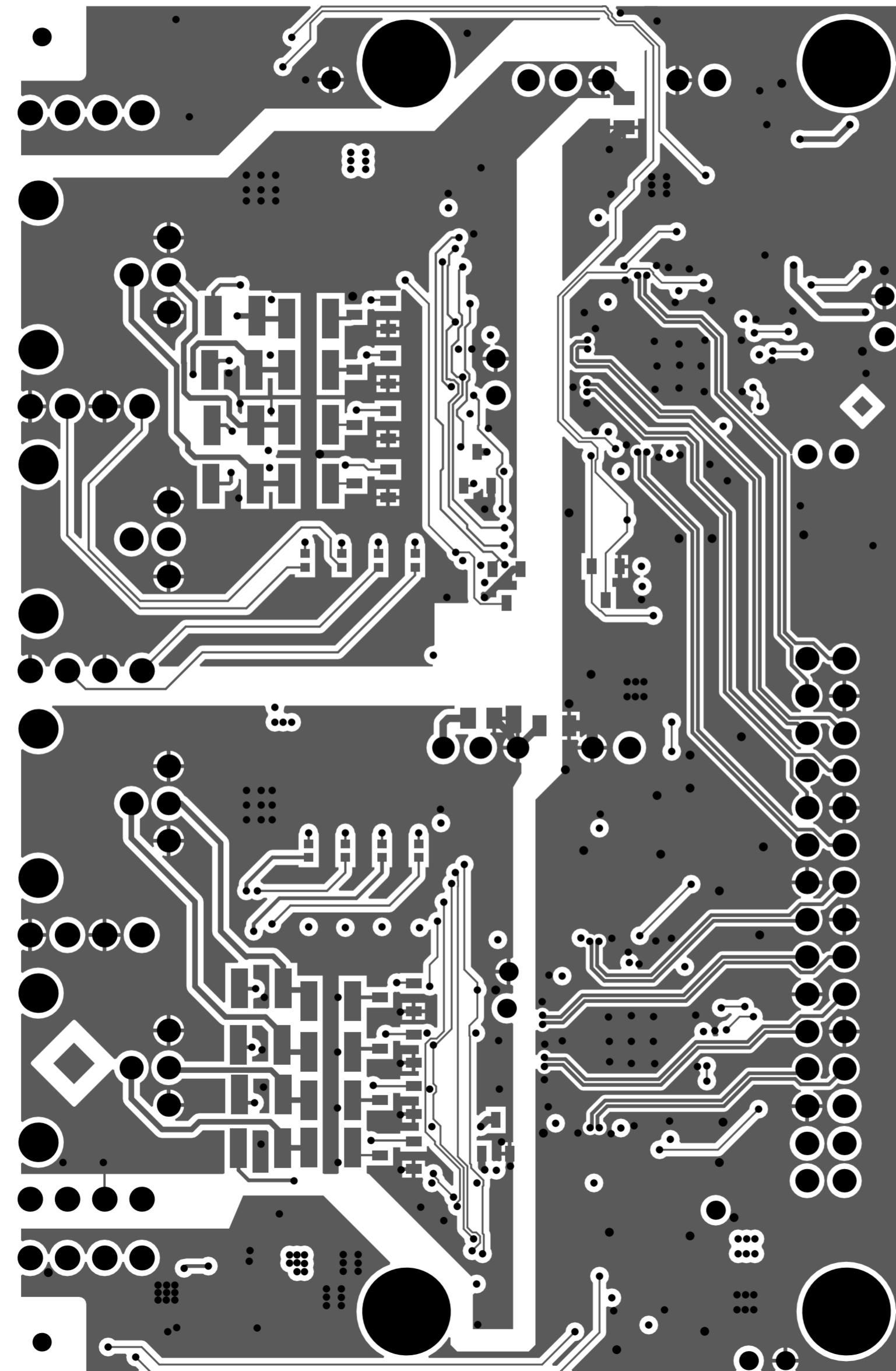


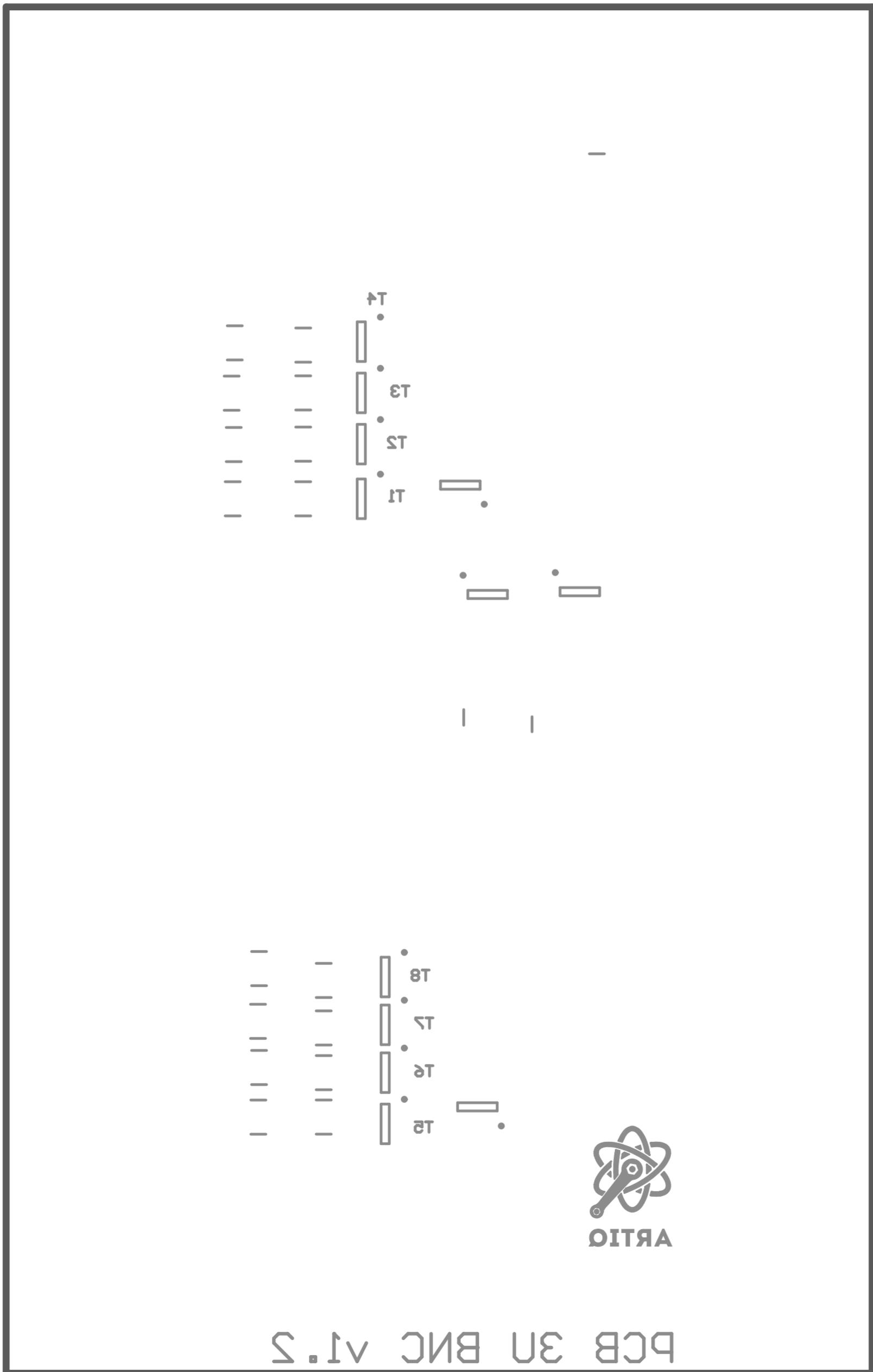


Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	TopOverlay				
2	TopSolder	Solder Resist	0.40mil	3.5	
3	TopLayer	Copper	1.40mil		
4	Dielectric1	FR-4	15.00mil	4.8	
5	Internal Plane 2	Copper	1.42mil		
6	Dielectric 3		5.00mil	4.2	
7	Internal Plane 1	Copper	1.42mil		
8	Dielectric2	FR-4	10.00mil	4.2	
9	BottomLayer	Copper	1.40mil		
10	BottomSolder	Solder Resist	0.40mil	3.5	
11	BottomOverlay				









PCB 3U BNC v1.2

